

Small Run PCB Assembly Capability

Assembly Method	Surface Mount, Thru-hole, Mixed Technology, Single and double-sided SMT/PTH, complex circuit on one side, BGA on both sides
Stencils	Laser-cut stainless-steel stencils
Components	Passive components smallest size 0201, Fine pitch components smallest size 8 Mils pitch, Leadless chip carriers/ BGA, VFBGA, FPGA & DFN, Connectors and terminals
Inspection	X-ray analysis, AOI, and Microscope to 20X
Solder Type	Leaded and Lead-free/RoHS compliant
Shape	Rectangular, Circular, Slots and cut-outs, and any Odd Shapes as per requirements
Available PCB Types	Flex, Rigid, Rigid-flex
Minimum Order	No Minimum Order, Support prototype proofing
Component Size	Smallest Components, BGA, Micro BGA, and Fine Pitch Parts Assembly
Testing	Flying Probe testing, ICT Testing, Automated Optical Inspection (AOI), Functional Testing, X-ray Inspection

High Volume PCB Assembly Capability

Types of Assembly	SMT, THT, Mixed Technology PCB Assembly Services, Single and double-sided SMT/PTH, complex circuit on one side, BGA on both sides
PCB Thickness	0.5mm~14.0mm
Copper Thickness	0.5 oz to 16 oz
Minimum Line Width	1.6mil
Minimum Line Spacing	1.6mil
PCB Size	50 mm×50 mm ~450 mm×1200 mm
Stencils	Laser-cut stainless-steel stencils
Components	Passive components smallest size 0201, Fine pitch components smallest size 8 Mils pitch, Leadless chip carriers/ BGA, VFBGA, FPGA & DFN, Connectors and terminals
Inspection	X-ray analysis, AOI, and Microscope to 20X
Solder Type	Leaded and Lead-free/RoHS compliant
Board Shape	Rectangular, Circular, Slots and cut-outs, and any Odd Shapes as per requirements
Min. Diameter / Space of BGA	0.2mm / 0.35mm
Board Type	Flex, Rigid, Rigid-flex
Minimum Order	No Minimum Order
Component Size	Smallest Components, BGA, Micro BGA, and Fine Pitch Parts Assembly
Types of Finishing	Carbon, Selective Gold Plating, SBOC(HASL), OSP, Hard and Soft Gold Immersion Gold, Immersion Silver, Immersion Tin
Supported File Formats	BOM: .xls, .csv, .xlsx Gerber (RS-274X) Centroid (XY, Pick-n-Place)
Testing	Flying Probe Test / Fixture Test, Impedance Test, Solderability Test, Thermal Shock Test, Hole Resistance Test, Micro Metallographic Section Analysis, etc